

**AMENDMENTS TO THE SPECIFICATION:**

Please amend the specification as follows:

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Please amend the first full paragraph beginning on line 5 as follows:

A further embodiment of the present invention is shown in Fig. 8. The embodiment shown in Fig. 8 is substantially the same as that shown in Fig. 5 but is constructed such that thermal vias 4 are not arranged only below emitter electrodes disposed nearest to ends (chip ends in the figure) of the semiconductor substrate 1. When a plurality of emitter electrodes 7 are arranged in rows on the semiconductor substrate 3, with each row having the emitter electrodes connected to the same emitter wiring, temperature of emitter base junctions in the vicinity of the respective emitter electrodes 7 is such that a plurality of emitters are high in temperature for those close to centers of the emitters thus arranged and low in temperature for those in peripheral portions thereof. With a high frequency element such as a power amplifier for portable phones, there is the need of making temperature distribution as uniform as possible because in particular, when HBTs are mounted, scatter in temperature of respective emitters arranged in parallel causes scatter in current flowing through the respective emitters to have the possibility that positive feedback is applied to cause oscillation of elements and eventual breakage thereof.